Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTION:**

1. **V+**
2. **OFFSET ADJ**
3. **INPUT**
4. **V-**
5. **OUTPUT**
6. **CH**
7. **LOGIC REF**
8. **LOGIC**

**.080”**

**.064”**

**4**

**3**

**2**

 **7 8 1**

**5**

**6**

**MASK**

**REF**

**H**

**LF198**

**Top Material: Al**

 **Backside Material: Si**

**Bond Pad Size: .004” X .004”**

**Backside Potential: V-**

**Mask Ref: LF198 H**

**APPROVED BY: DK DIE SIZE .064” X .080” DATE: 9/20/17**

**MFG: NATIONAL THICKNESS .013” P/N: LF398**

**DG 10.1.2**

#### Rev B, 7/1